



# VIS30724

## 30V N-Channel SGT MOSFET

### General Description

- SGT MOSFET Technology
- Low  $R_{DS(ON)}$  at 4.5V  $V_{GS}$
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

### Applications

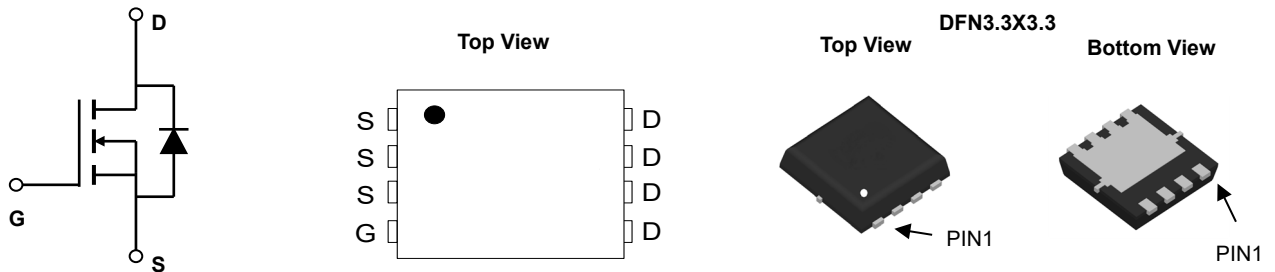
- General DC/DC Converters
- VRM Vcore for Notebook and Server
- Battery Power Management
- Motor Drive Bridge Switch

### Product Summary

$V_{DS}$		30V
$I_D$	(at $V_{GS}=10V$ )	40A
$R_{DS(ON)}$	(at $V_{GS}=10V$ , typ)	2.4m $\Omega$
$R_{DS(ON)}$	(at $V_{GS}=4.5V$ , typ)	3.5m $\Omega$

100% UIS Tested

100%  $R_g$  Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
VIS30724	DFN3.3x3.3	Tape & Reel	5000

### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>(5)</sup>	$T_C=25^\circ C$	40	A
	$T_C=100^\circ C$	TBD	A
Pulsed Drain Current <sup>(3)</sup>	$I_{DM}$	150	A
Continuous Drain Current	$T_A=25^\circ C$	TBD	A
	$T_A=100^\circ C$	TBD	A
Avalanche Current <sup>(3)</sup>	$I_{AS}$	33	A
Avalanche Energy $L=0.1mH$ <sup>(3)</sup>	$E_{AS}$	54	mJ
Power Dissipation <sup>(2)</sup>	$T_C=25^\circ C$	TBD	W
	$T_C=100^\circ C$	TBD	W
Power Dissipation <sup>(1)</sup>	$T_A=25^\circ C$	TBD	W
	$T_A=100^\circ C$	TBD	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>(1)</sup>	$R_{\theta JA}$	30		$^\circ C/W$
Maximum Junction-to-Ambient <sup>(1,4)</sup>		Steady-State	60	$^\circ C/W$
Maximum Junction-to-Case	$R_{\theta JC}$	2.4		$^\circ C/W$



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### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			1 5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.4	1.6	2.0	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A T <sub>J</sub> =125°		2.4 TBD	3.0	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A		3.5	4.6	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A				S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1A, V <sub>GS</sub> =0V		0.7		V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				TBD	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		2600		pF
C <sub>oss</sub>	Output Capacitance			988		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			80		pF
R <sub>g</sub>	Gate resistance	f=1MHz		1.5		Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =20A		34		nC
Q <sub>g</sub> (4.5V)	Total Gate Charge			17		nC
Q <sub>gs</sub>	Gate Source Charge			TBD		nC
Q <sub>gd</sub>	Gate Drain Charge			TBD		nC
t <sub>D(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =0.75Ω, R <sub>GEN</sub> =3Ω		TBD		ns
t <sub>r</sub>	Turn-On Rise Time			TBD		ns
t <sub>D(off)</sub>	Turn-Off Delay Time			TBD		ns
t <sub>f</sub>	Turn-Off Fall Time			TBD		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=200A/μs		TBD		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =20A, di/dt=200A/μs		40		nC
<ol style="list-style-type: none"> <li>R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The Power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> ≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.</li> <li>The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.</li> <li>Single pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.</li> <li>R<sub>θJA</sub> is the sum of the thermal impedance from junction to case R<sub>θJC</sub> and case to ambient.</li> <li>The maximum current rating is package limited.</li> </ol>						

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